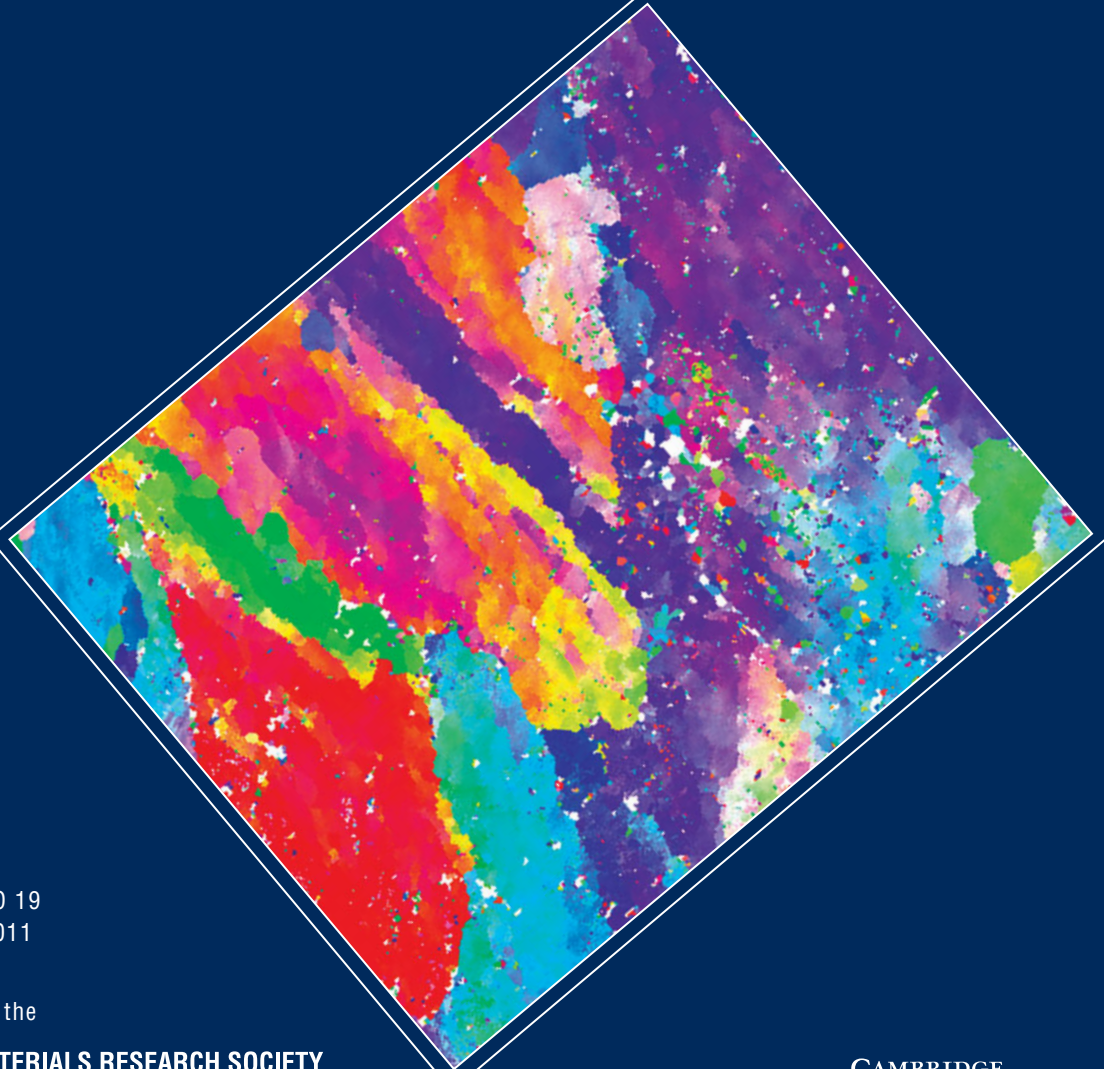




Journal of
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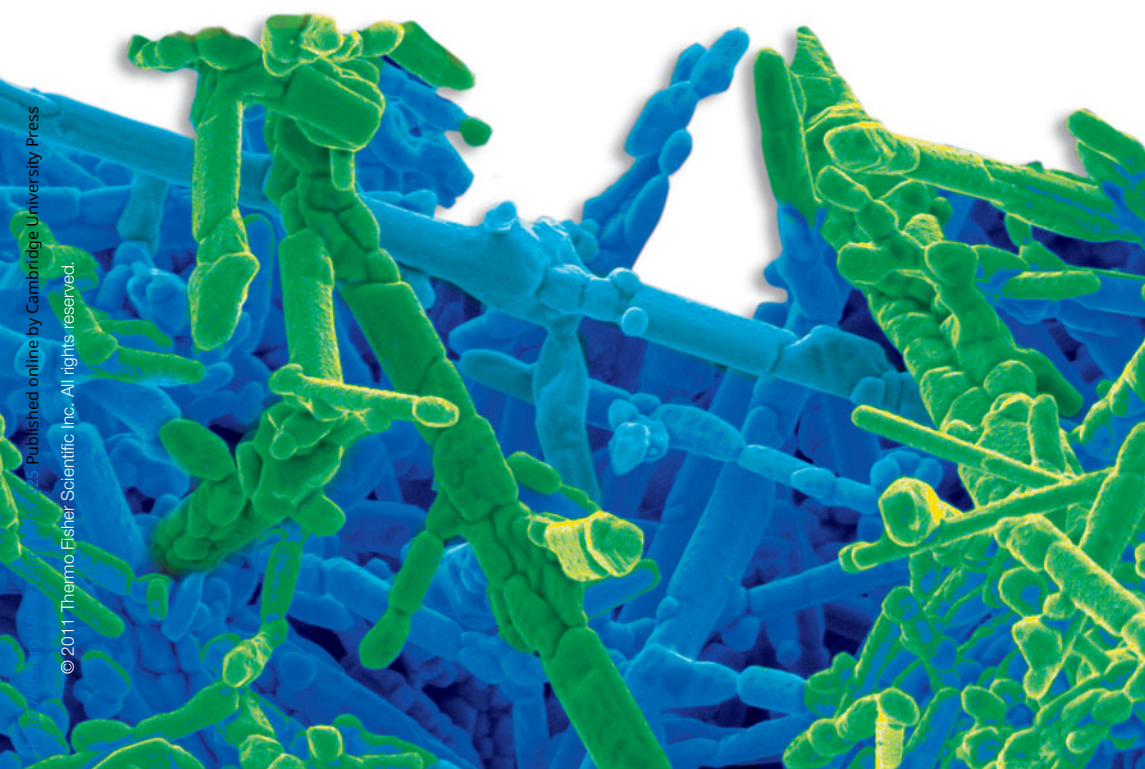
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Cover: Electron backscatter diffraction patterns of Ni-Ti shape memory alloy sample that was deformed in the instability region of the processing map. [V.V. Shastry, B. Maji, M. Krishnan, and U. Ramamurty: High-temperature deformation processing maps for a NiTiCu shape memory alloy. p. 2484.]

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